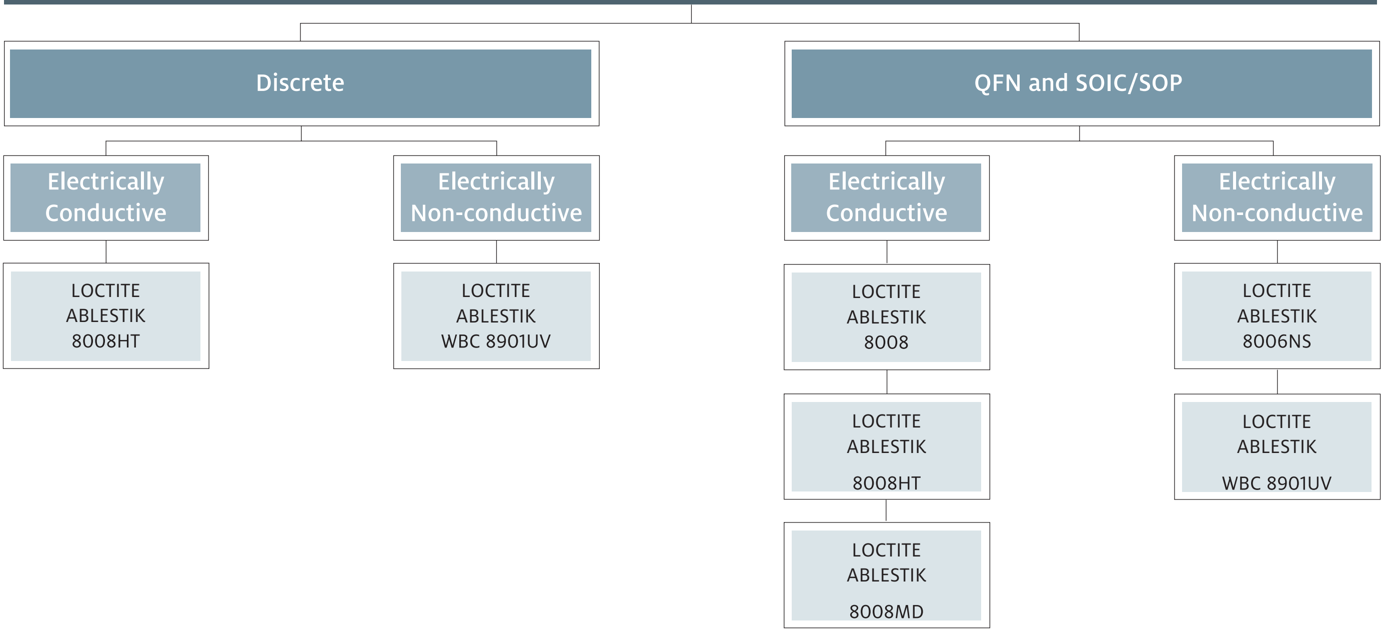
Henkel Solutions for Leadframe Packaging
Wafer Backside Coatings

WAFER BACKSIDE COATINGS (WBC) FOR WIREBOND LEADFRAME PACKAGING



- Discrete
  - Electrically Conductive
    - LOCTITE ABLESTIK 8008HT
  - Electrically Non-conductive
    - LOCTITE ABLESTIK WBC 8901UV
- QFN and SOIC/SOP
  - Electrically Conductive
    - LOCTITE ABLESTIK 8008
    - LOCTITE ABLESTIK 8008HT
    - LOCTITE ABLESTIK 8008MD
  - Electrically Non-conductive
    - LOCTITE ABLESTIK 8006NS
    - LOCTITE ABLESTIK WBC 8901UV

ELECTRICALLY CONDUCTIVE WAFER BACKSIDE COATINGS (WBC)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	DIE SIZE (mm)	SUBSTRATE FINISH	MOISTURE SENSITIVITY LEVEL, MSL	VOLUME RESISTIVITY (Ohm·cm)	THERMAL CONDUCTIVITY (W/m·K)	RECOMMENDED CURE
LOCTITE ABLESTIK 8008	Ag-filled die attach wafer backside coating adhesive	• Excellent stencil printing and low surface roughness • Void-free bondline without bleed • Oven B-stage and snap or oven cure	≤ 3 x 3	Cu, Ag or PPF	L1 260°C capable	1.0×10^{-4}	2.2	60 sec. at 230°C (snap)
LOCTITE ABLESTIK 8008HT	Ag-filled die attach wafer backside coating adhesive	• Applied by stencil printing • Void-free bondline without bleed • Oven B-stage and snap or oven cure	≤ 1 x 1	Cu, Ag or PPF	L1 260°C capable	6.0×10^{-5}	11.0	20 sec. at 170°C (snap)
LOCTITE ABLESTIK 8008MD	Ag-filled die attach wafer backside coating adhesive	• Applied by stencil printing • Low stress • Good substrate wetting • Oven B-stage and oven cure	≤ 4 x 4	Cu, Ag or PPF	L1 260°C capable	5.0×10^{-4}	6.0	10 min. ramp and 60 min. hold at 115°C

ELECTRICALLY NON-CONDUCTIVE WAFER BACKSIDE COATINGS (WBC)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	DIE SIZE (mm)	SUBSTRATE FINISH	MOISTURE SENSITIVITY LEVEL, MSL	MODULUS AT 25°C (MPa)	CTE (ppm/°C)		RECOMMENDED CURE
							Below T_g	Above T_g	
LOCTITE ABLESTIK 8006NS	Alumina/silica-filled, epoxy die attach wafer backside coating adhesive	• Applied by stencil or screen printing • Consistent bondline downto 25 µm with minimal die tilt • Oven B-stage and oven cure	≤ 4 x 4	Cu, Ag or PPF	L1 260°C capable	4,376	33	136	2 hr. at 160°C
LOCTITE ABLESTIK WBC 8901UV	Die attach wafer backside coating adhesive	• Wide process windows • 5 to 60 µm bondline control • Low viscosity before B-stage • Can be spray coated on Dicing Before Grinding (DBG) wafers • UV B-stage and oven cure	≤ 1 x 1	Cu, Ag or PPF	L2 260°C capable	3,585	45	142	15 min. ramp and 30 min. hold at 90°C + 4 min. ramp and 45 min. hold at 120°C

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